Electronic Version

Stylesheet Version v1.1.1

Claims

[c1] 1. A chip structure, comprising:

a chip, having an active surface and at least a bonding pad disposed on the active surface;

a first passivation layer, disposed on the active surface, comprising at least a first opening exposing the bonding pad; and

a spacing pad, disposed on the bonding pad within the first opening.

[c2] 2. The chip structure of claim 1, wherein the structure further comprises a metallic bump pad connected to the spacing pad and covering the peripheral surface around the first opening.

[c3] 3. The chip structure of claim 2, further comprising a second passivation layer disposed over the first passivation layer such that the second passivation layer comprises at least a second opening that exposes the metallic bump pad.

[c4] 4. The chip structure of claim 3, further comprising an under-bump metallic layer disposed on the top surface of the metallic bump pad and over the peripheral area

around the second opening.

[c5] 5. The chip structure of claim 4, wherein further comprising a conductive bump connected to the under-bump metallic layer.

[c6] 6. The chip structure of claim 3, further comprising a conductive bump connected to the metallic bump pad.

[c7] 7. The chip structure of claim 1, further comprising an under-bump metallic layer covering a top surface of the spacing pad and the peripheral area around the first opening.

[c8] 8. The chip structure of claim 7, further comprising a conductive bump connected to the under-bump metallic layer.

[c9] 9. A conductive structure on the bonding pad of a chip having an active surface and at least a bonding pad disposed on the active surface, the conductive structure comprising:

a spacing pad, disposed on the bonding pad, comprising a first surface and a corresponding second surface such that the first surface is in contact with the bonding pad;

a metallic bump pad, having a base in contact with the second surface of the spacing pad and a planar top surface; and

a conductive bump, having a base in contact with the planar top surface of the metallic bump pad.